P32FG15SL

Power MOSFETs 150V, 32A, N-channel

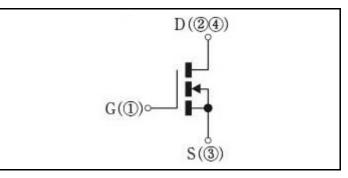
Feature

- N-channel
- SMD
- Low Ron
- 4.5V Gate Drive
- Low Capacitance
- Pb free terminal
- · RoHS:Yes

OUTLINE



Equivalent circuit



Absolute Maximum Ratings (unless otherwise specified : Tc=25°C)

Item	Symbol	Conditions	Ratings	Unit
Storage temperrature	Tstg		-55 to 150	°C
Channel tempertature	Tch		150	°C
Drain-source voltage	V _{DSS}		150	V
Gate-source voltage	V _{GSS}		±20	V
Continuous drain current(DC)	I _D		32	A
Continuous drain current(Peak)	I _{DP}	Pulse width 10µs, duty=1/100	96	A
Total power dissipation	P _T		100	W
Single avalanche current	I _{AS}	Starting Tch=25°C Tch≦150°C	22	Α
Single avalanche energy	E _{AS}	Starting Tch=25°C Tch≦150°C	28	mJ

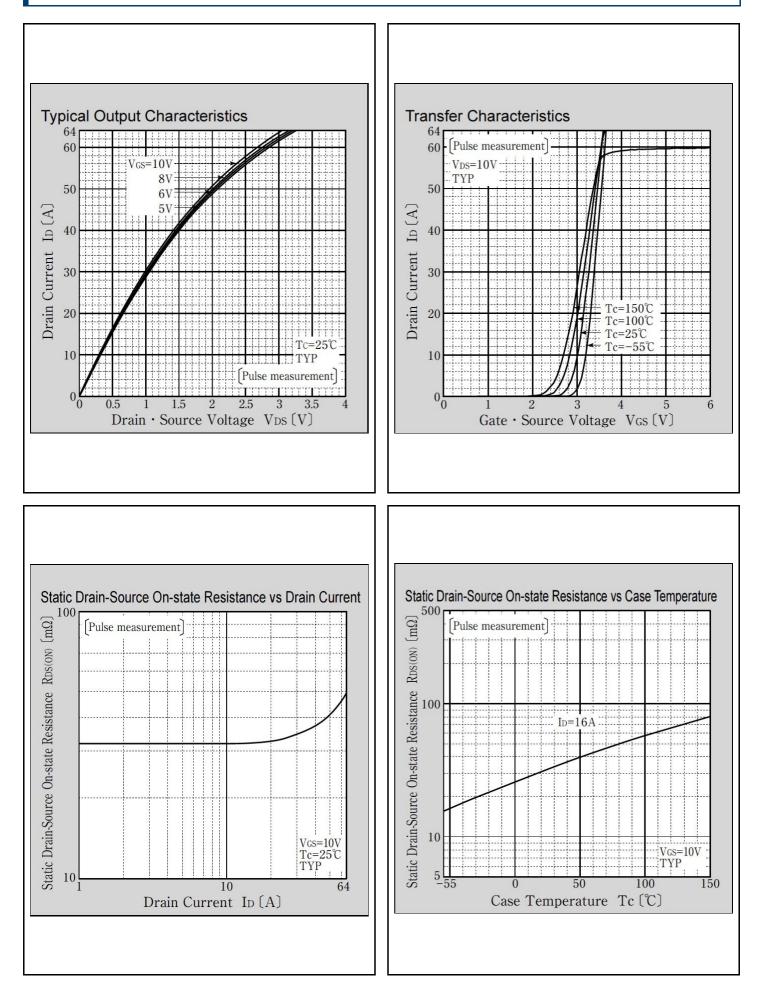
* : See the original Specifications

Electrical Characteristics	(unless otherwise specified : Tc=25°C)

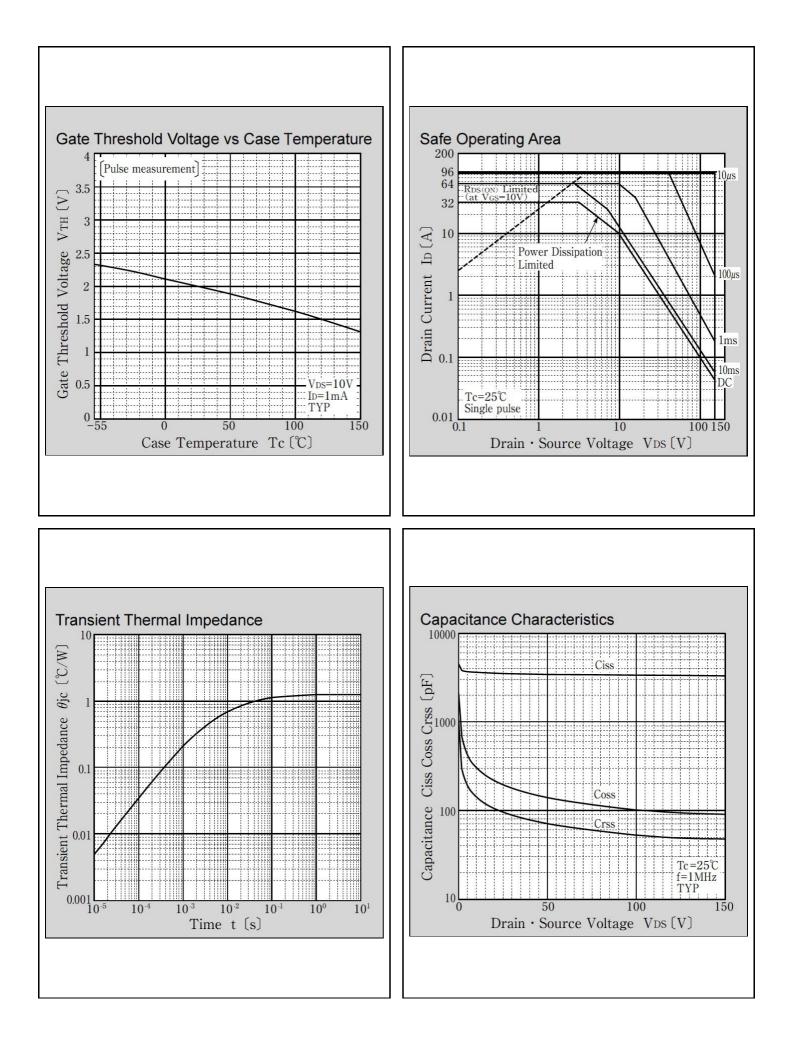
Item	Symbol	Conditions		Ratings		
			MIN	ТҮР	MAX	Unit
Drain-Source breakdown voltage	V _{(BR)DSS}	ID=1mA, VGS=0V	150			V
Zero gate voltage drain current	I _{DSS}	VDS=150V, VGS=0V			1	μA
Gate-source leakage current	I _{GSS}	VGS=±20V, VDS=0V			±0.1	μA
Forward transconductance	9fs	ID=16A, VDS=10V	12	24		S
Static drain-source on-state resistance	R _{DS(ON)}	ID=16A, VGS=10V		0.032	0.04	Ω
Static drain-source on-state resistance	R _{DS(ON)}	ID=16A, VGS=4.5V		0.034	0.045	Ω
Gate threshold voltage	Vth	ID=1mA, VDS=10V	1.5	2	2.5	V
Source-drain diode forward voltage	V_{SD}	IS=32A, VGS=0V			1.5	V
Thermal resistance	Rth(j-c)	Junction to case			1.25	°C/W
Total gate charge	Qg	VDD=120V, VGS=10V, ID=32A		72		nC
Gate to source charge	Qgs	VDD=120V, VGS=10V, ID=32A		13		nC
Gate to drain charge	Qgd	VDD=120V, VGS=10V, ID=32A		19		nC
Input capacitance	Ciss	VDS=25V, VGS=0V, f=1MHz		3530		pF
Reverce transfer capacitnce	Crss	VDS=25V, VGS=0V, f=1MHz		95		pF
Output capacitance	Coss	VDS=25V, VGS=0V, f=1MHz		195		pF
Turn-on delay time	td(on)	ID=16A, RL=4.69Ω, VDD=75V, Rg=0Ω, VGS(+)=10V, VGS(-)=0V		8		ns
Rise time	tr	ID=16A, RL=4.69Ω, VDD=75V, Rg=0Ω, VGS(+)=10V, VGS(-)=0V		15		ns
Turn-off delay time	td(off)	ID=16A, RL=4.69Ω, VDD=75V, Rg=0Ω, VGS(+)=10V, VGS(-)=0V		45		ns
Fall time	tf	ID=16A, RL=4.69Ω, VDD=75V, Rg=0Ω, VGS(+)=10V, VGS(-)=0V		30		ns
Diode reverse recovery time	trr	IF=32A, VGS=0V, di/dt=100A/µs		73		ns
Diode reverse recovery charge	Qrr	IF=32A, VGS=0V, di/dt=100A/µs		210		nC

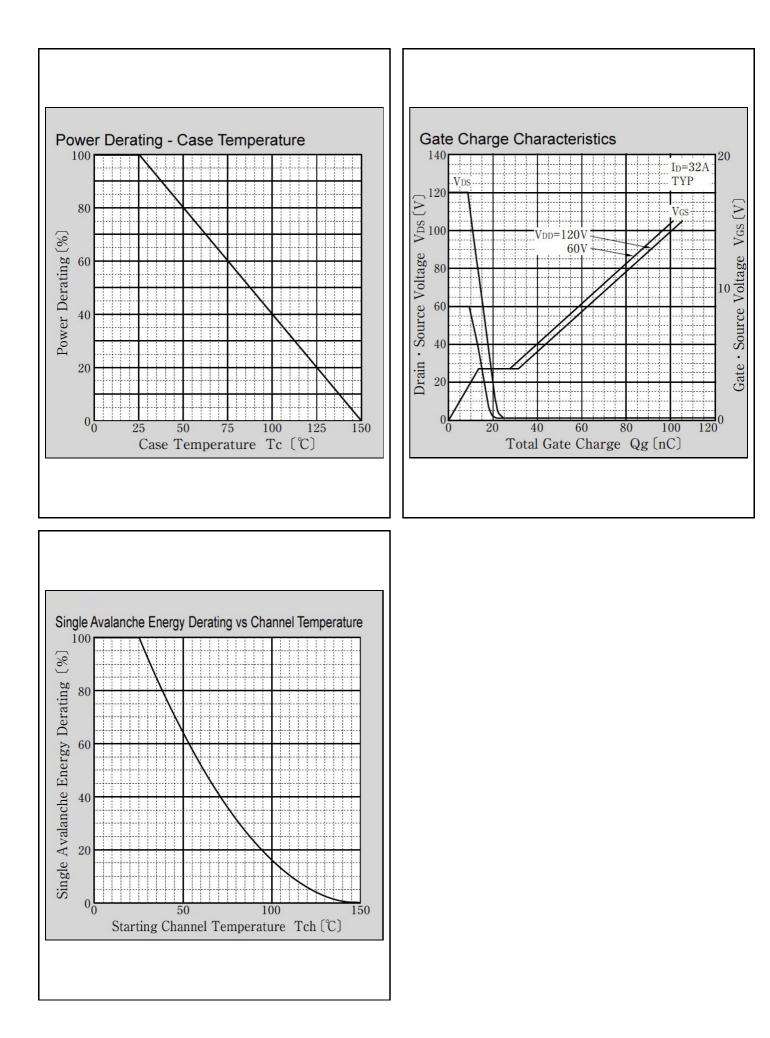
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CHARACTERISTIC DIAGRAMS



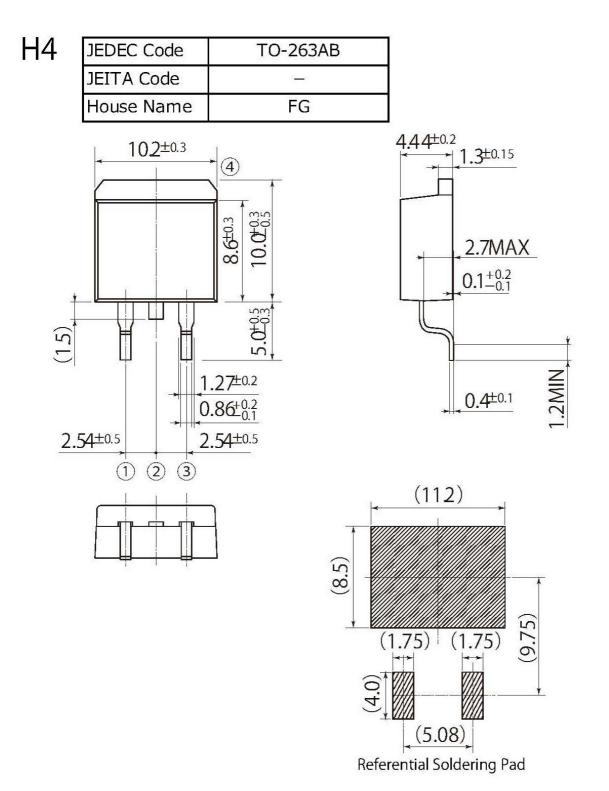
3/7





unit:mm

scale: 3/1



Optimize soldering pad to the board design and soldering condition.

Notes

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